



Dual, Serial Input 16-Bit Multiplying Digital-to-Analog Converter

FEATURES

- **Relative Accuracy: 1 LSB Max**
- **Differential Nonlinearity: 1 LSB Max**
- **2-mA Full-Scale Current $\pm 20\%$, with $V_{REF} = \pm 10\text{ V}$**
- **0.5 μs Settling Time**
- **Midscale or Zero-Scale Reset**
- **Separate 4Q Multiplying Reference Inputs**
- **Reference Bandwidth: 10 MHz**
- **Reference Dynamics: -105 dB THD**
- **SPI™-Compatible 3-Wire Interface: 50 MHz**
- **Double Buffered Registers to Enable Simultaneous Multichannel Update**
- **Internal Power On Reset**
- **Industry-Standard Pin Configuration**

APPLICATIONS

- **Automatic Test Equipment**
- **Instrumentation**
- **Digitally Controlled Calibration**

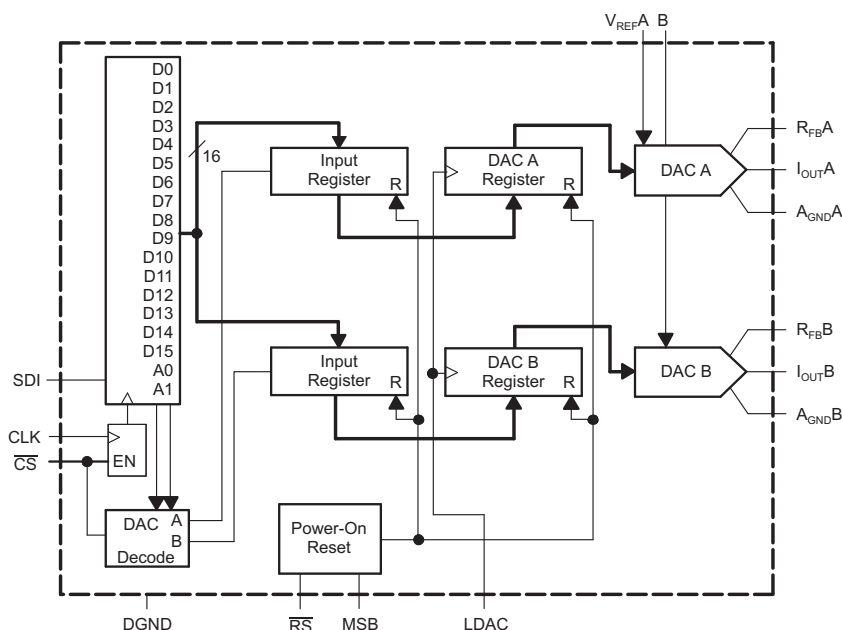
DESCRIPTION

The DAC8812 is a dual, 16-bit, current-output digital-to-analog converter (DAC) designed to operate from a single 2.7 V to 5.5 V supply.

The applied external reference input voltage V_{REF} determines the full-scale output current. An internal feedback resistor (R_{FB}) provides temperature tracking for the full-scale output when combined with an external I-to-V precision amplifier.

A double-buffered, serial data interface offers high-speed, 3-wire, SPI and microcontroller compatible inputs using serial data in (SDI), clock (CLK), and a chip-select (\overline{CS}). A common level-sensitive load DAC strobe (LDAC) input allows simultaneous update of all DAC outputs from previously loaded input registers. Additionally, an internal power-on reset forces the output voltage to zero at system turn-on. An MSB pin allows system reset assertion (\overline{RS}) to force all registers to zero code when MSB = 0, or to half-scale code when MSB = 1.

The DAC8812 is available in an TSSOP-16 package.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION⁽¹⁾

| PRODUCT | MINIMUM RELATIVE ACCURACY (LSB) | DIFFERENTIAL NONLINEARITY (LSB) | SPECIFIED TEMPERATURE RANGE | PACKAGE- LEAD | PACKAGE DESIGNATOR | ORDERING NUMBER | TRANSPORT MEDIA, QUANTITY |
|----------|--|---------------------------------------|-----------------------------------|------------------|-----------------------|--------------------|---------------------------------|
| DAC8812C | ±1 | ±1 | –40°C to 85°C | TSSOP-16 | PW | DAC8812ICPW | Tube, 90 |
| | | | | | | DAC8812ICPWR | Tape and Reel, 2500 |
| DAC8812B | ±2 | ±1 | –40°C to 85°C | TSSOP-16 | PW | DAC8812IBPW | Tube, 90 |
| | | | | | | DAC8812IBPWR | Tape and Reel, 2500 |

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

| | | DAC8812 | UNIT |
|---|-----|--------------------------------|------|
| V_{DD} to GND | | – 0.3 to 7 | V |
| V_{REFX} , R_{FBX} to GND | | –18 to 18 | V |
| Digital logic inputs to GND | | – 0.3 to $V_{DD} + 0.3$ | V |
| $V(I_{OUT})$ to GND | | – 0.3 to $V_{DD} + 0.3$ | V |
| A_{GNDX} to DGND | | –0.3 to +0.3 | V |
| Input current to any pin except supplies | | ±50 | mA |
| Package power dissipation | | $(T_{Jmax} - T_A)/\theta_{JA}$ | W |
| Thermal resistance, θ_{JA} | | 100 | °C/W |
| Maximum junction temperature (T_{Jmax}) | | 150 | °C |
| Operating temperature range | | – 40 to 85 | °C |
| Storage temperature range | | – 65 to 150 | °C |
| ESD ratings | HBM | 4 | kV |
| | CDM | 1 | kV |

- (1) Stresses above those listed under absolute maximum ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS⁽¹⁾

V_{DD} = 2.7 V to 5.5 V, I_{OUTX} = Virtual GND, A_{GNDX} = 0 V, V_{REFA} , B = 10 V, T_A = full operating temperature range, unless otherwise noted.

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNIT |
|---|------------|---------------------------------|-----|-------|-----|--------|
| STATIC PERFORMANCE⁽²⁾ | | | | | | |
| Resolution | | | | | 16 | Bits |
| Relative accuracy | INL | DAC8812B | | | ±2 | LSB |
| | | DAC8812C | | | ±1 | LSB |
| Differential nonlinearity | DNL | | | | ±1 | LSB |
| Output leakage current | I_{OUTX} | Data = 0000h, T_A = +25°C | | | 10 | nA |
| | | Data = 0000h, T_A = T_A max | | | 20 | nA |
| Full-scale gain error | G_{FSE} | Data = FFFFh | | ±0.75 | ±4 | mV |
| Full-scale tempco ⁽³⁾ | TCV_{FS} | | | 1 | | ppm/°C |
| Feedback resistor | R_{FBX} | V_{DD} = 5 V | | 5 | | kΩ |
| REFERENCE INPUT⁽³⁾ | | | | | | |
| V_{REFX} range | V_{REFX} | | –15 | | 15 | V |
| Input resistance | R_{REFX} | | 4 | 5 | 6 | kΩ |
| Input resistance match | R_{REFX} | Channel-to-channel | | 1 | | % |
| Input capacitance | C_{REFX} | | | 5 | | pF |
| ANALOG OUTPUT⁽³⁾ | | | | | | |
| Output current | I_{OUTX} | Data = FFFFh | 1.6 | | 2.5 | mA |
| Output capacitance | C_{OUTX} | Code-dependent | | 50 | | pF |
| LOGIC INPUTS⁽³⁾ | | | | | | |
| Input low voltage | V_{IL} | V_{DD} = 2.7 V | | | 0.6 | V |
| | | V_{DD} = 5 V | | | 0.8 | V |
| Input high voltage | V_{IH} | V_{DD} = 2.7 V | 2.1 | | | V |
| | | V_{DD} = 5 V | 2.4 | | | V |
| Input leakage current | I_{IL} | | | | 1 | μA |
| Input capacitance | C_{IL} | | | | 10 | pF |
| INTERFACE TIMING⁽⁴⁾ | | | | | | |
| Clock width high | t_{CH} | | 10 | | | ns |
| Clock width low | t_{CL} | | 10 | | | ns |
| \overline{CS} to Clock setup | t_{CSS} | | 0 | | | ns |
| Clock to \overline{CS} hold | t_{CSH} | | 10 | | | ns |
| Clock to SDO prop delay | t_{PD} | | 2 | | 20 | ns |
| Load DAC pulsewidth | t_{LDAC} | | 20 | | | ns |
| Data setup | t_{DS} | | 10 | | | ns |
| Data hold | t_{DH} | | 10 | | | ns |
| Load setup | t_{LDS} | | 5 | | | ns |
| Load hold | t_{LDH} | | 25 | | | ns |

(1) Specifications subject to change without notice.

(2) All static performance tests (except I_{OUT}) are performed in a closed-loop system using an external precision OPA277 I-to-V converter amplifier. The DAC8812 R_{FB} terminal is tied to the amplifier output. Typical values represent average readings measured at +25°C.

(3) These parameters are specified by design and not subject to production testing.

(4) All input control signals are specified with $t_R = t_F = 2.5$ ns (10% to 90% of 3 V) and timed from a voltage level of 1.5 V.

ELECTRICAL CHARACTERISTICS (continued)

$V_{DD} = 2.7\text{ V to }5.5\text{ V}$, $I_{OUTX} = \text{Virtual GND}$, $A_{GNDX} = 0\text{ V}$, $V_{REFA, B} = 10\text{ V}$, $T_A = \text{full operating temperature range}$, unless otherwise noted.

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNIT |
|--|-----------------------|--|-----|------|--------|------------------------------|
| SUPPLY CHARACTERISTICS | | | | | | |
| Power supply range | $V_{DD\text{ RANGE}}$ | | 2.7 | | 5.5 | V |
| Positive supply current | I_{DD} | Logic inputs = 0 V, $V_{DD} = +4.5\text{ V to }+5.5\text{ V}$ | | 2 | 5 | μA |
| | | Logic inputs = 0 V, $V_{DD} = +2.7\text{ V to }+3.6\text{ V}$ | | 1 | 2.5 | μA |
| Power dissipation | P_{DISS} | Logic inputs = 0 V | | | 0.0275 | mW |
| Power supply sensitivity | P_{SS} | $\Delta V_{DD} = \pm 5\%$ | | | 0.006 | % |
| AC CHARACTERISTICS⁽⁵⁾⁽⁶⁾ | | | | | | |
| Output voltage settling time | t_s | To $\pm 0.1\%$ of full-scale, Data = 0000h to FFFFh to 0000h | | 0.3 | | μs |
| | | To $\pm 0.0015\%$ of full-scale, Data = 0000h to FFFFh to 0000h | | 0.5 | | μs |
| Reference multiplying BW | BW -3 dB | $V_{REFX} = 100\text{ mV}_{RMS}$, Data = FFFFh, $C_{FB} = 3\text{ pF}$ | | 10 | | MHz |
| DAC glitch impulse | Q | $V_{REFX} = 10\text{ V}$, Data = 7FFFh to 8000h to 7FFFh | | 5 | | nV/s |
| Feedthrough error | V_{OUTX}/V_{REFX} | Data = 0000h, $V_{REFX} = 100\text{ mV}_{RMS}$, $f = 100\text{ kHz}$ | | -70 | | dB |
| Crosstalk error | V_{OUTA}/V_{REFB} | Data = 0000h, $V_{REFB} = 100\text{ mV}_{RMS}$, Adjacent channel, $f = 100\text{ kHz}$ | | -100 | | dB |
| Digital feedthrough | Q | $\overline{CS} = 1$ and $f_{CLK} = 1\text{ MHz}$ | | 1 | | nV/s |
| Total harmonic distortion | THD | $V_{REF} = 5\text{ V}_{PP}$, Data = FFFFh, $f = 1\text{ kHz}$ | | -105 | | dB |
| Output spot noise voltage | e_n | $f = 1\text{ kHz}$, BW = 1 Hz | | 12 | | $\text{nV}/\sqrt{\text{Hz}}$ |

(5) These parameters are specified by design and not subject to production testing.

(6) All ac characteristic tests are performed in a closed-loop system using an THS4011 I-to-V converter amplifier.

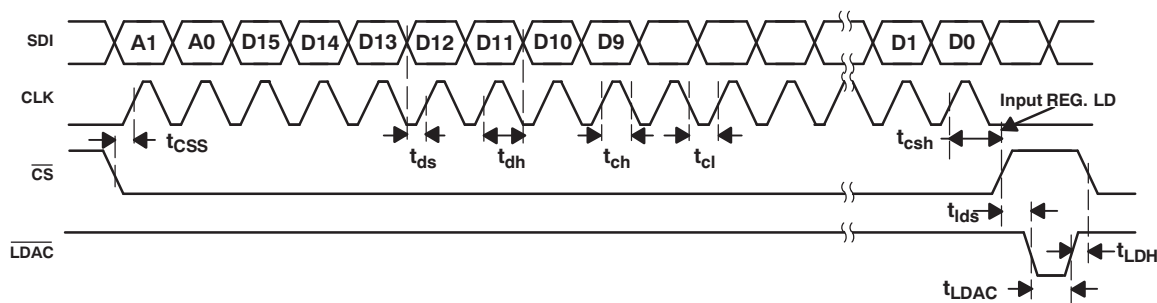
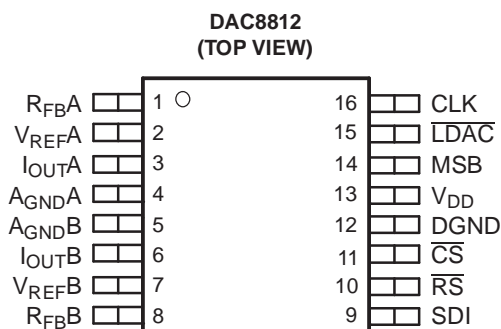
PARAMETER MEASUREMENT INFORMATION

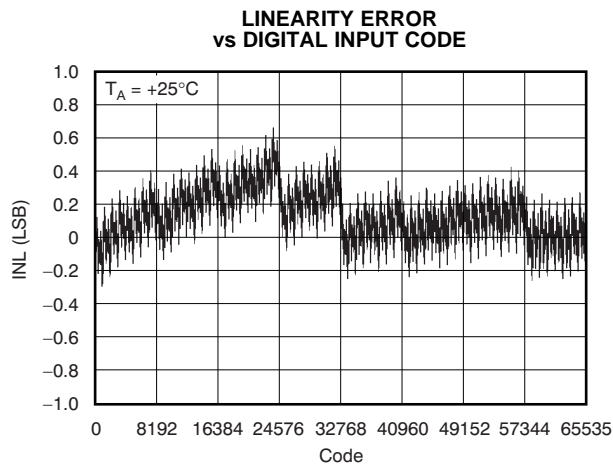
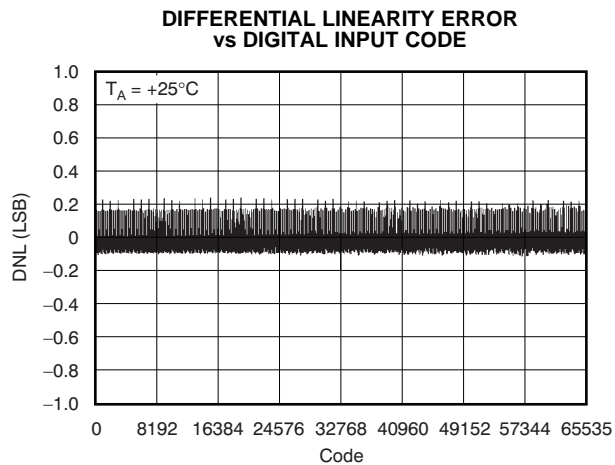
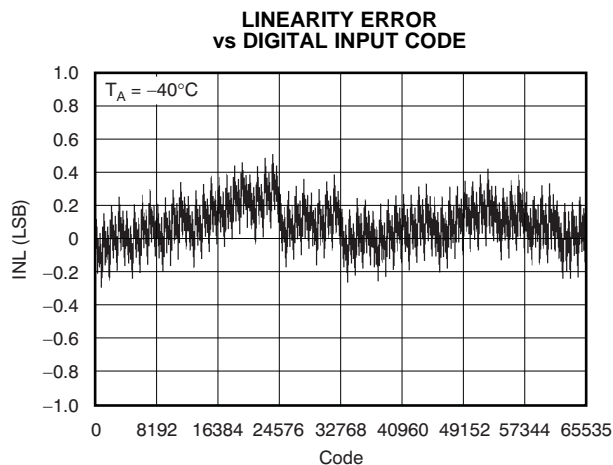
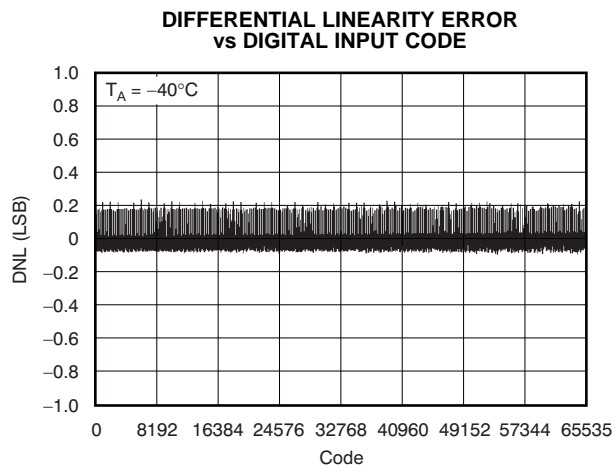
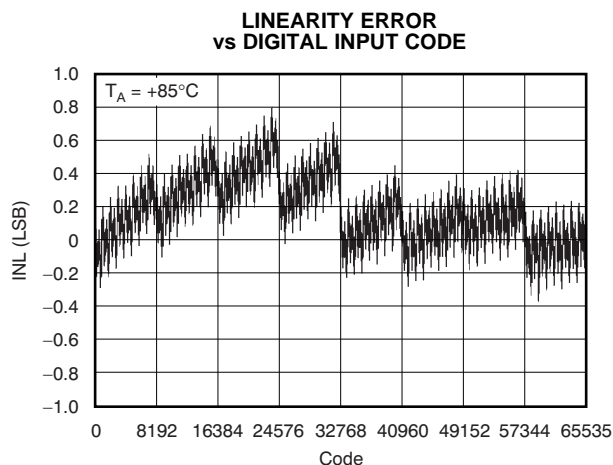
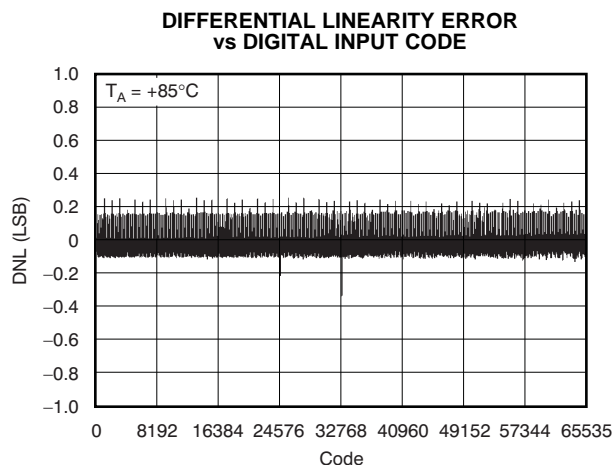
Figure 1. DAC8812 Timing Diagram

PIN CONFIGURATION



PIN DESCRIPTION

| PIN | NAME | DESCRIPTION |
|-----|--------------------|---|
| 1 | R _{FB} A | Establish voltage output for DAC A by connecting to external amplifier output. |
| 2 | V _{REF} A | DAC A Reference voltage input terminal. Establishes DAC A full-scale output voltage. Can be tied to V _{DD} pin. |
| 3 | I _{OUT} A | DAC A Current output. |
| 4 | A _{GNDA} | DAC A Analog ground. |
| 5 | A _{GNDB} | DAC B Analog ground. |
| 6 | I _{OUT} B | DAC B Current output. |
| 7 | V _{REF} B | DAC B Reference voltage input terminal. Establishes DAC B full-scale output voltage. Can be tied to V _{DD} pin. |
| 8 | R _{FB} B | Establish voltage output for DAC B by connecting to external amplifier output. |
| 9 | SDI | Serial data input; data loads directly into the shift register. |
| 10 | \overline{RS} | Reset pin; active low input. Input registers and DAC registers are set to all 0s or midscale. Register data = 0x0000 when MSB = 0. Register data = 0x8000 when MSB = 1 for DAC8812. |
| 11 | \overline{CS} | Chip-select; active low input. Disables shift register loading when high. Transfers serial register data to input register when \overline{CS} goes high. Does not affect LDAC operation. |
| 12 | DGND | Digital ground. |
| 13 | V _{DD} | Positive power-supply input. Specified range of operation 2.7 V to 5.5 V. |
| 14 | MSB | MSB bit sets output to either 0 or midscale during a RESET pulse (\overline{RS}) or at system power-on. Output equals zero scale when MSB = 0 and midscale when MSB = 1. MSB pin can be permanently tied to ground or V _{DD} . |
| 15 | \overline{LDAC} | Load DAC register strobe; level sensitive active low. Transfers all input register data to the DAC registers. Asynchronous active low input. See Table 2 for operation. |
| 16 | CLK | Clock input. Positive edge clocks data into shift register. |

TYPICAL CHARACTERISTICS: $V_{DD} = 5\text{ V}$ At $T_A = 25^\circ\text{C}$, $+V_{DD} = 5\text{ V}$, unless otherwise noted.**Channel A****Figure 2.****Figure 3.****Figure 4.****Figure 5.****Figure 6.****Figure 7.**

TYPICAL CHARACTERISTICS: $V_{DD} = 5\text{ V}$ (continued)

At $T_A = 25^\circ\text{C}$, $+V_{DD} = 5\text{ V}$, unless otherwise noted.

Channel B

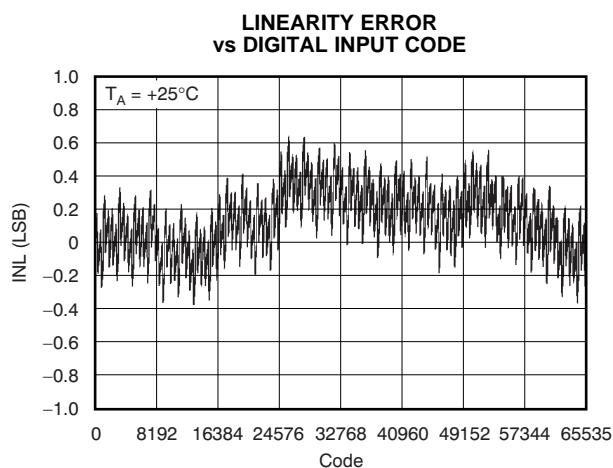


Figure 8.

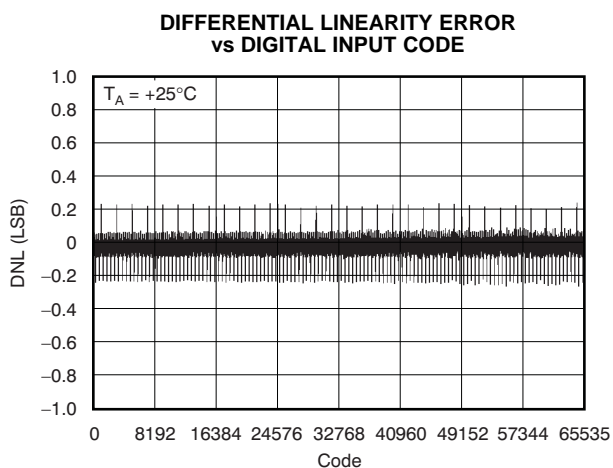


Figure 9.

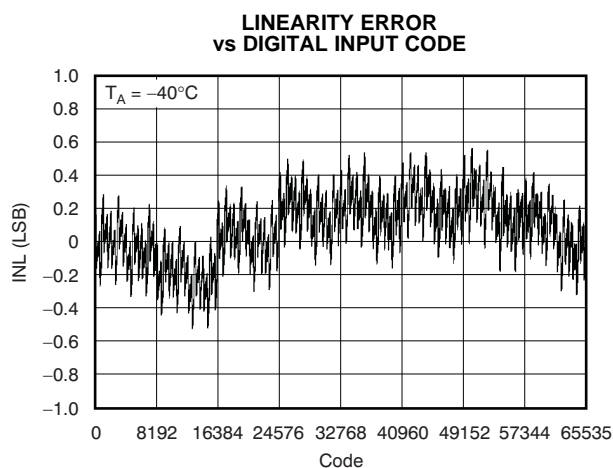


Figure 10.

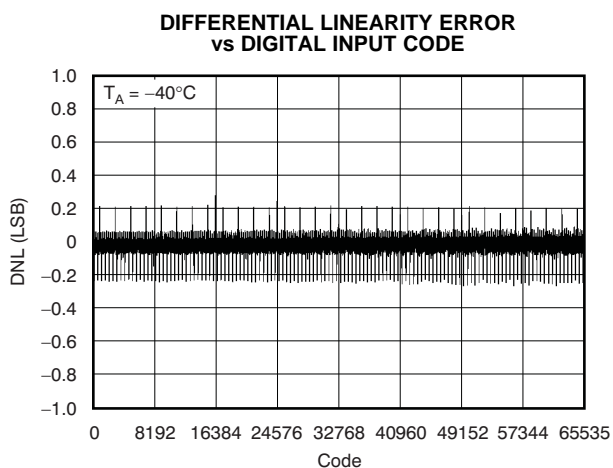


Figure 11.

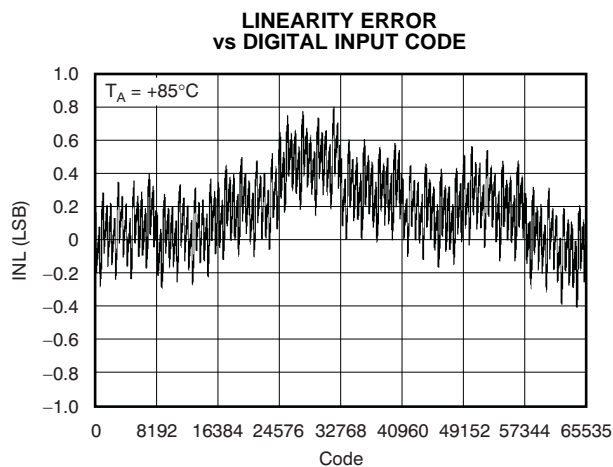


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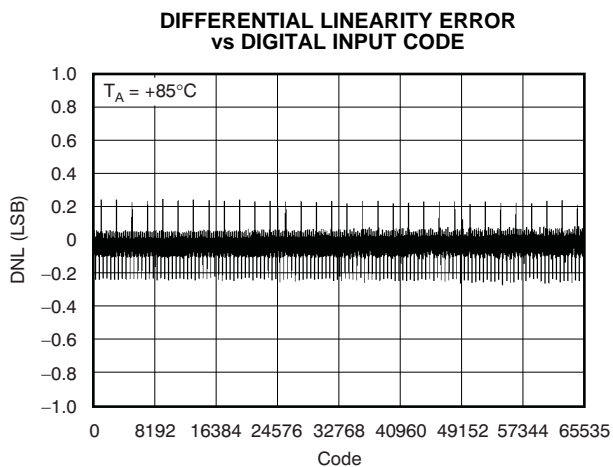


Figure 13.

TYPICAL CHARACTERISTICS: $V_{DD} = 5\text{ V}$ (continued)

At $T_A = 25^\circ\text{C}$, $+V_{DD} = 5\text{ V}$, unless otherwise noted.

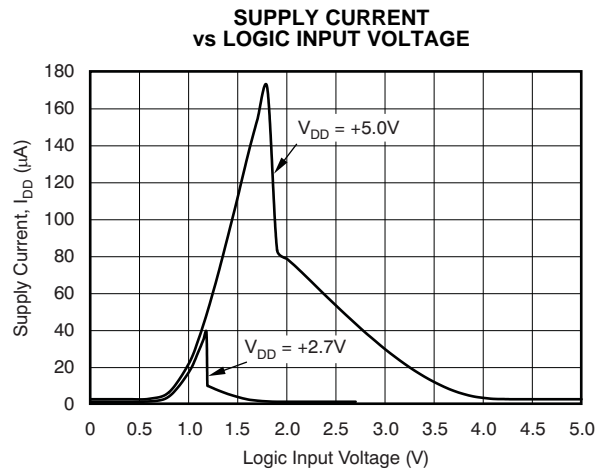


Figure 14.

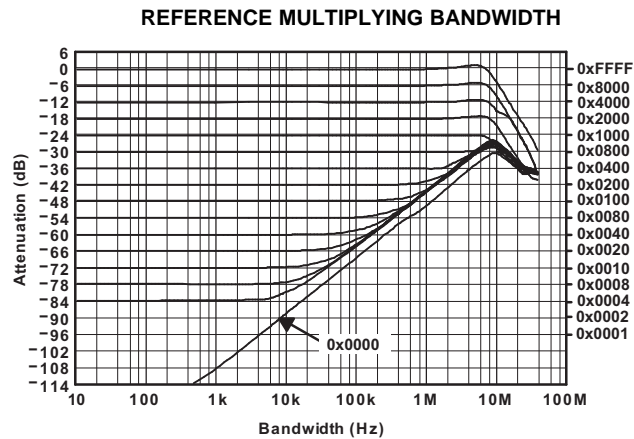


Figure 15.

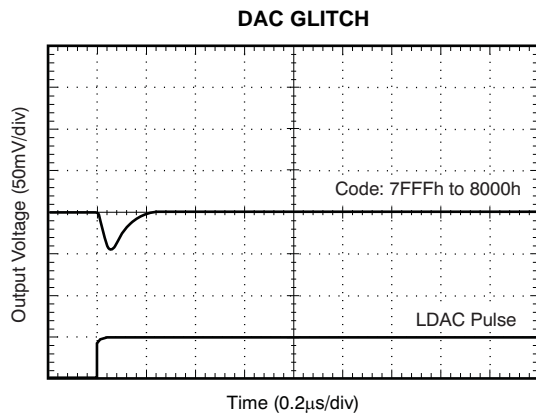


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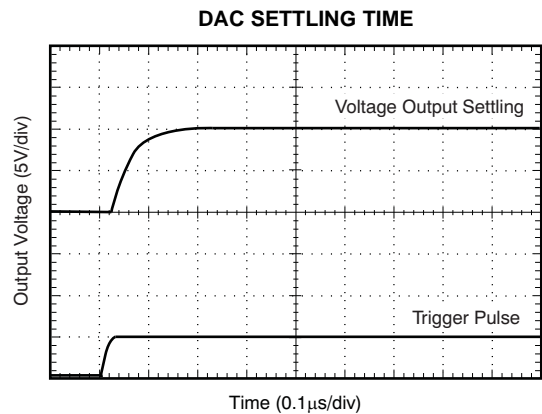


Figure 17.

TYPICAL CHARACTERISTICS: $V_{DD} = 2.7\text{ V}$

At $T_A = 25^\circ\text{C}$, $+V_{DD} = 2.7\text{ V}$, unless otherwise noted.

Channel A

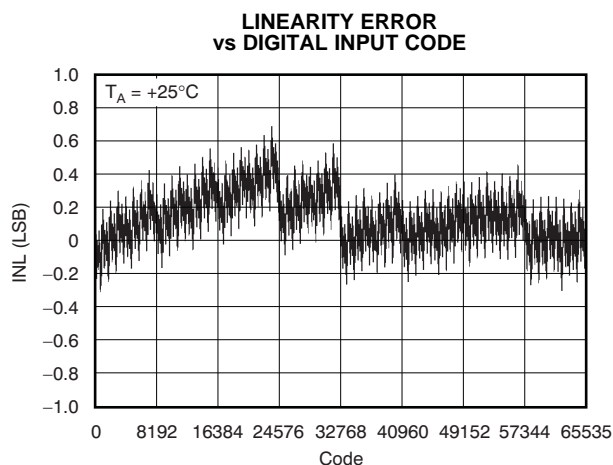


Figure 18.

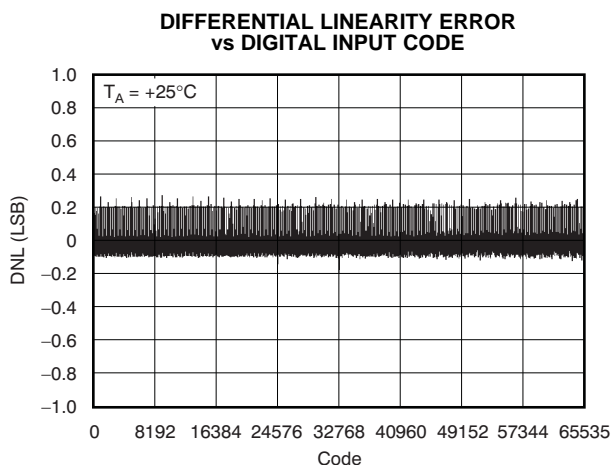


Figure 19.

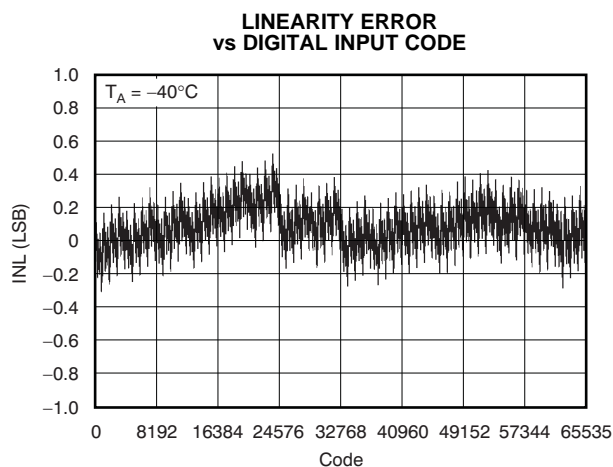


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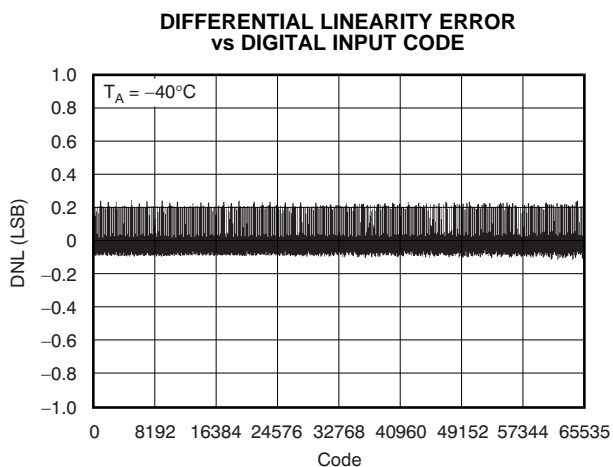


Figure 21.

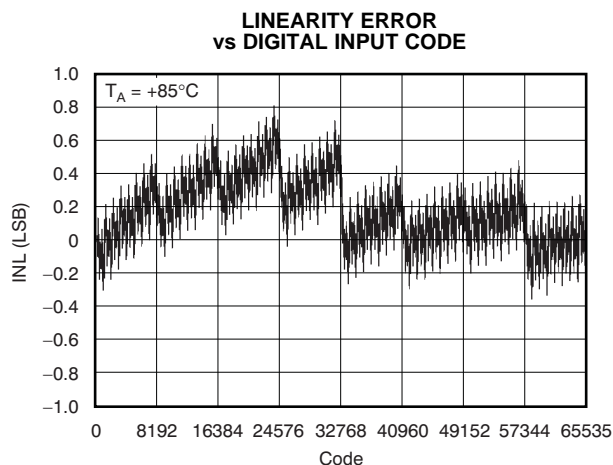


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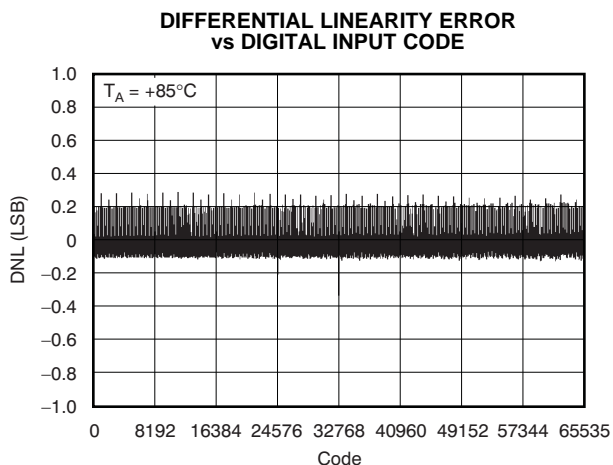
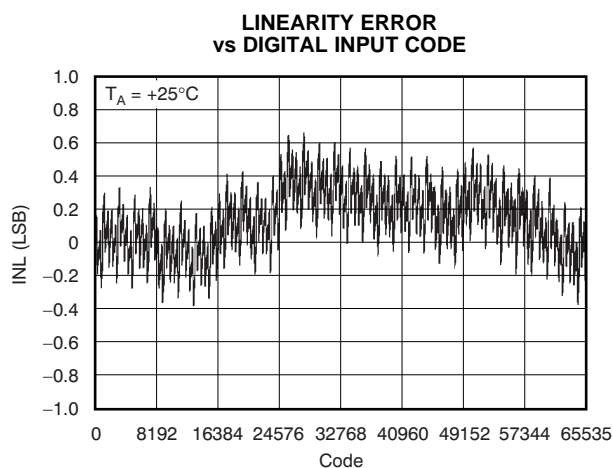
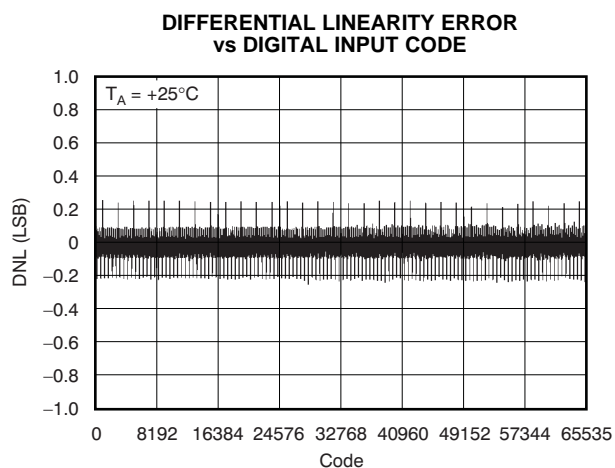
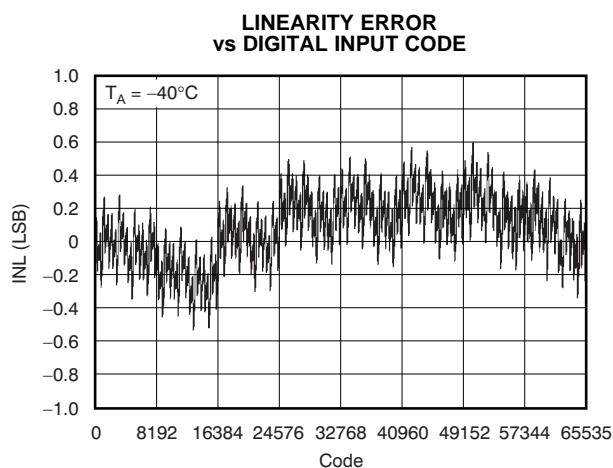
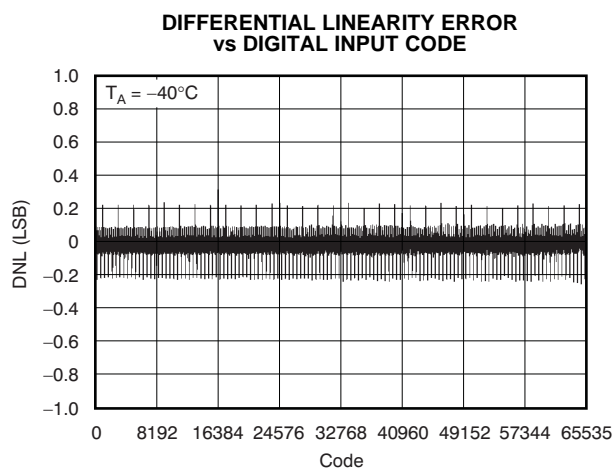
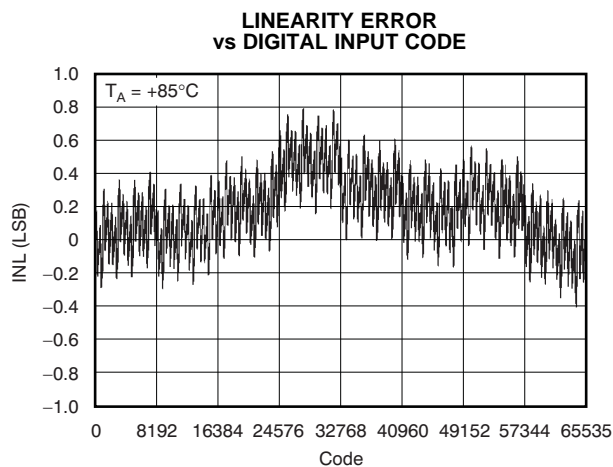
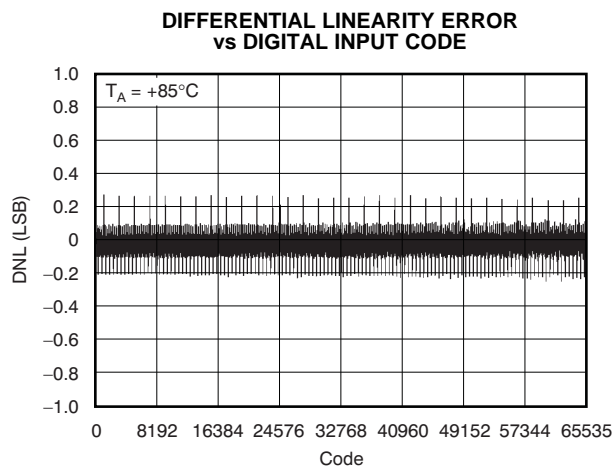


Figure 23.

TYPICAL CHARACTERISTICS: $V_{DD} = 2.7\text{ V}$ (continued)

At $T_A = 25^\circ\text{C}$, $+V_{DD} = 2.7\text{ V}$, unless otherwise noted.

Channel B**Figure 24.****Figure 25.****Figure 26.****Figure 27.****Figure 28.****Figure 29.**

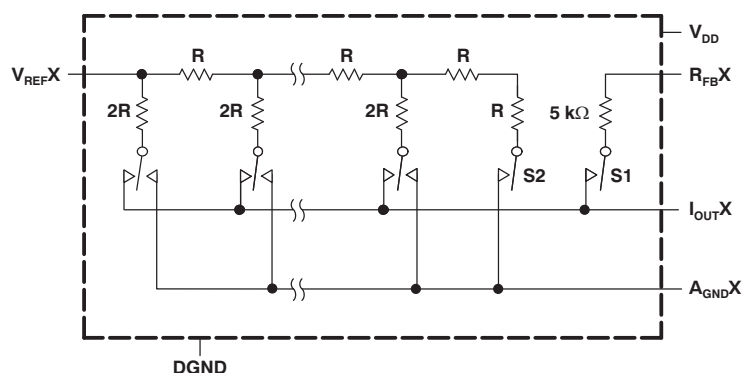
THEORY OF OPERATION

CIRCUIT OPERATION

The DAC8812 contains two 16-bit, current-output, digital-to-analog converters (DACs). Each DAC has its own independent multiplying reference input. The DAC8812 uses a 3-wire, SPI-compatible serial data interface, with a configurable asynchronous \overline{RS} pin for half-scale (MSB = 1) or zero-scale (MSB = 0) preset. In addition, an \overline{LDAC} strobe enables two channel simultaneous updates for hardware synchronized output voltage changes.

Digital-to-Analog Converters

The DAC8812 contains two current-steering R-2R ladder DACs. Figure 30 shows a typical equivalent DAC. Each DAC contains a matching feedback resistor for use with an external I-to-V converter amplifier. The R_{FBX} pin is connected to the output of the external amplifier. The I_{OUTX} terminal is connected to the inverting input of the external amplifier. The A_{GNDX} pin should be Kelvin-connected to the load point in the circuit requiring the full 16-bit accuracy.



Digital interface connections omitted for clarity.
Switches S1 and S2 are closed, V_{DD} must be powered.

Figure 30. Typical Equivalent DAC Channel

The DAC is designed to operate with both negative or positive reference voltages. The V_{DD} power pin is only used by the logic to drive the DAC switches on and off. Note that a matching switch is used in series with the internal 5 kΩ feedback resistor. If users are attempting to measure the value of R_{FB} , power must be applied to V_{DD} in order to achieve continuity. The DAC output voltage is determined by V_{REF} and the digital data (D) according to Equation 1:

$$V_{OUT} = -V_{REF} \times \frac{D}{65536} \quad (1)$$

Note that the output polarity is opposite of the V_{REF} polarity for dc reference voltages.

The DAC is also designed to accommodate ac reference input signals. The DAC8812 accommodates input reference voltages in the range of –15 V to 15 V. The reference voltage inputs exhibit a constant nominal input resistance of 5 kΩ, ±20%. On the other hand, DAC outputs I_{OUTA} and B are code-dependent and produce various output resistances and capacitances.

The choice of external amplifier should take into account the variation in impedance generated by the DAC8812 on the amplifiers' inverting input node. The feedback resistance, in parallel with the DAC ladder resistance, dominates output voltage noise. For multiplying mode applications, an external feedback compensation capacitor, C_{FB} (4 pF to 20 pF typical), may be needed to provide a critically damped output response for step changes in reference input voltages.

Figure 15 shows the gain vs frequency performance at various attenuation settings using a 3 pF external feedback capacitor connected across the I_{OUTX} and R_{FBX} terminals. In order to maintain good analog performance, power-supply bypassing of 0.01 μ F, in parallel with 1 μ F, is recommended. Under these conditions, clean power supply with low ripple voltage capability should be used. Switching power supplies is usually not suitable for this application due to the higher ripple voltage and P_{SS} frequency-dependent characteristics. It is best to derive the DAC8812 5-V supply from the system analog supply voltages (do not use the digital 5-V supply); see **Figure 31**.

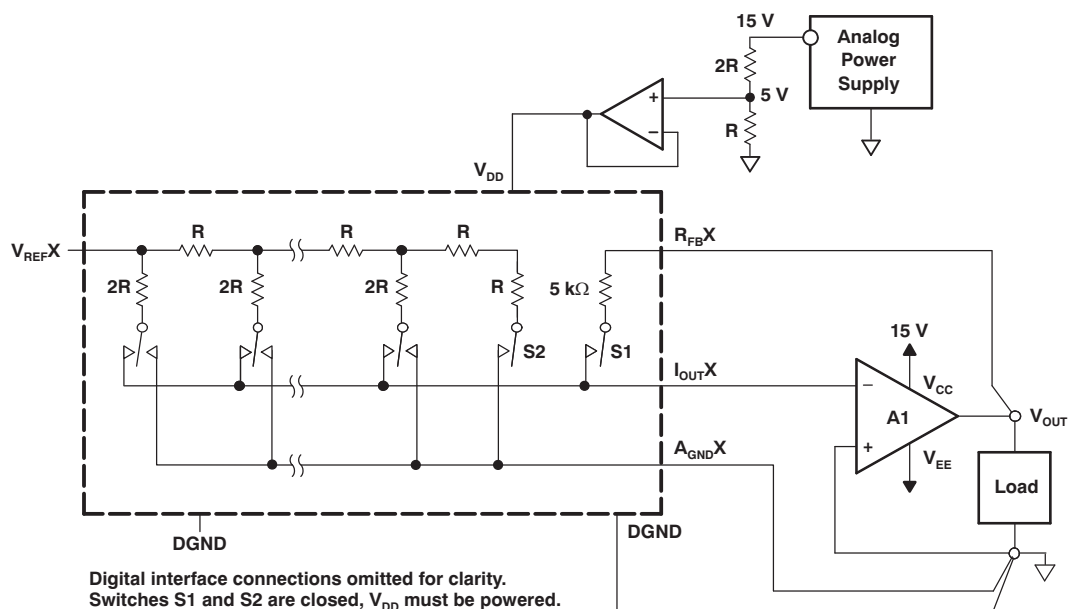


Figure 31. Recommended Kelvin-Sensed Hookup

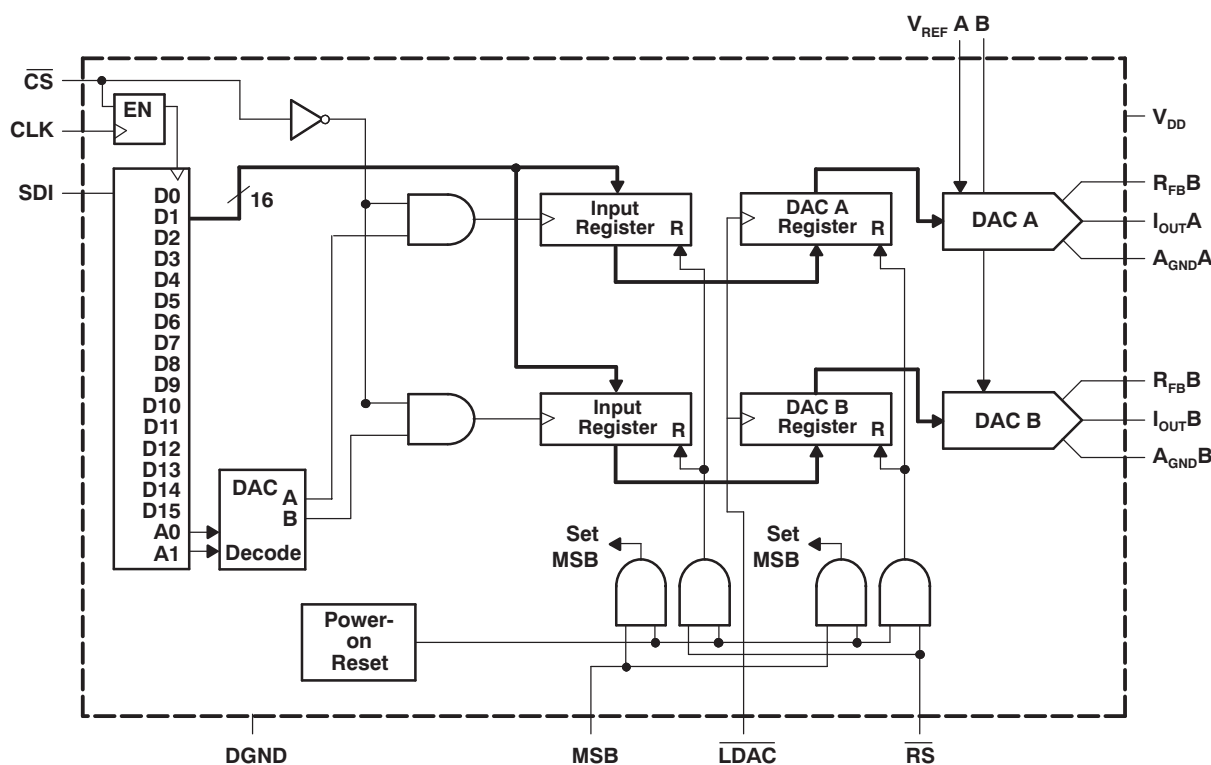


Figure 32. System Level Digital Interfacing

SERIAL DATA INTERFACE

The DAC8812 uses a 3-wire ($\overline{\text{CS}}$, SDI, CLK) SPI-compatible serial data interface. Serial data of the DAC8812 is clocked into the serial input register in an 18-bit data-word format. MSB bits are loaded first. Table 1 defines the 18 data-word bits for the DAC8812.

Data is placed on the SDI pin, and clocked into the register on the positive clock edge of CLK subject to the data setup and data hold time requirements specified in the *Interface Timing* specifications of the [Electrical Characteristics](#). Data can only be clocked in while the $\overline{\text{CS}}$ chip select pin is active low. For the DAC8812, only the last 18 bits clocked into the serial register are interrogated when the $\overline{\text{CS}}$ pin returns to the logic high state.

Since most microcontrollers output serial data in 8-bit bytes, three right-justified data bytes can be written to the DAC8812. Keeping the $\overline{\text{CS}}$ line low between the first, second, and third byte transfers will result in a successful serial register update.

Once the data is properly aligned in the shift register, the positive edge of the $\overline{\text{CS}}$ initiates the transfer of new data to the target DAC register, determined by the decoding of address bits A1 and A0. For the DAC8812, Table 1, Table 2, Table 3, and Figure 1 define the characteristics of the software serial interface.

Table 1. Serial Input Register Data Format, Data Loaded MSB First⁽¹⁾

| Bit | B17 (MSB) | B16 | B15 | B14 | B13 | B12 | B11 | B10 | B9 | B8 | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 (LSB) |
|------|--------------|-----|-----|-----|-----|-----|-----|-----|----|----|----|----|----|----|----|----|----|-------------|
| Data | A1 | A0 | D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |

- (1) Only the last 18 bits of data clocked into the serial register (address + data) are inspected when the $\overline{\text{CS}}$ line positive edge returns to logic high. At this point an internally-generated load strobe transfers the serial register data contents (bits D15-D0) to the decoded DAC-input-register address determined by bits A1 and A0. Any extra bits clocked into the DAC8812 shift register are ignored; only the last 18 bits clocked in are used. If double-buffered data is not needed, the $\overline{\text{LDAC}}$ pin can be tied logic low to disable the DAC registers.

Table 2. Control Logic Truth Table⁽¹⁾

| $\overline{\text{CS}}$ | CLK | $\overline{\text{LDAC}}$ | $\overline{\text{RS}}$ | MSB | SERIAL SHIFT REGISTER | INPUT REGISTER | DAC REGISTER |
|------------------------|-------------|--------------------------|------------------------|-----|--------------------------------------|---|----------------------|
| H | X | H | H | X | No effect | Latched | Latched |
| L | L | H | H | X | No effect | Latched | Latched |
| L | $\uparrow+$ | H | H | X | Shift register data advanced one bit | Latched | Latched |
| L | H | H | H | X | No effect | Latched | Latched |
| $\uparrow+$ | L | H | H | X | No effect | Selected DAC updated with current SR contents | Latched |
| H | X | L | H | X | No effect | Latched | Transparent |
| H | X | H | H | X | No effect | Latched | Latched |
| H | X | $\uparrow+$ | H | X | No effect | Latched | Latched |
| H | X | H | L | 0 | No effect | Latched data = 0000h | Latched data = 0000h |
| H | X | H | L | H | No effect | Latched data = 8000h | Latched data = 8000h |

- (1) $\uparrow+$ = Positive logic transition; X = Do not care

Table 3. Address Decode

| A1 | A0 | DAC DECODE |
|----|----|-----------------|
| 0 | 0 | None |
| 0 | 1 | DAC A |
| 1 | 0 | DAC B |
| 1 | 1 | DAC A and DAC B |

Figure 33 shows the equivalent logic interface for the key digital control pins for the DAC8812.

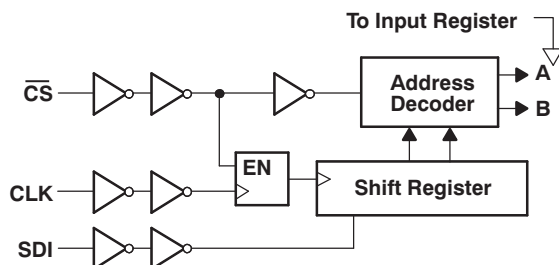


Figure 33. DAC8812 Equivalent Logic Interface

Two additional pins \overline{RS} and MSB provide hardware control over the preset function and DAC register loading. If these functions are not needed, the \overline{RS} pin can be tied to logic high. The asynchronous input \overline{RS} pin forces all input and DAC registers to either the zero-code state (MSB = 0), or the half-scale state (MSB = 1).

POWER ON RESET

When the V_{DD} power supply is turned on, an internal reset strobe forces all the Input and DAC registers to the zero-code state or half-scale, depending on the MSB pin voltage. The V_{DD} power supply should have a smooth positive ramp without drooping, in order to have consistent results, especially in the region of $V_{DD} = 1.5\text{ V}$ to 2.3 V . The DAC register data stays at zero or half-scale setting until a valid serial register data load takes place.

ESD Protection Circuits

All logic-input pins contain back-biased ESD protection zener diodes connected to ground (DGND) and V_{DD} as shown in Figure 34.

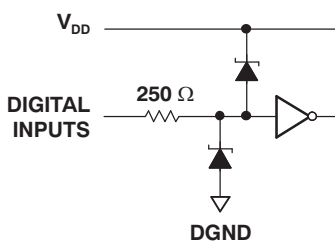


Figure 34. Equivalent ESD Protection Circuits

PCB LAYOUT

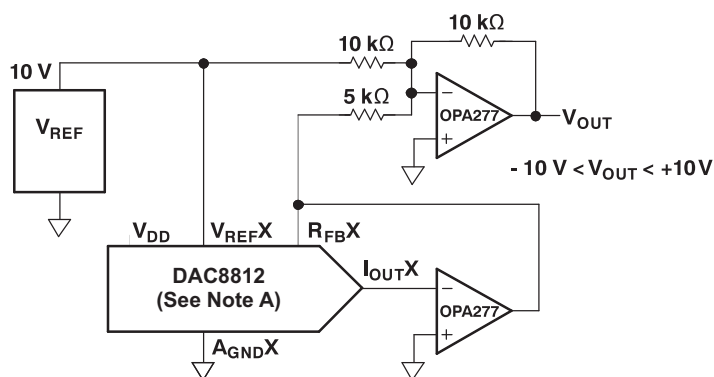
The DAC8812 is a high-accuracy DAC that can have its performance compromised by grounding and printed circuit board (PCB) lead trace resistance. The 16-bit DAC8812 with a 10-V full-scale range has an LSB value of 153 mV. The ladder and associated reference and analog ground currents for a given channel can be as high as 2 mA. With this 2-mA current level, a series wiring and connector resistance of only 76 mΩ will cause 1 LSB of voltage drop. The preferred PCB layout for the DAC8812 is to have all $A_{GND}X$ pins connected directly to an analog ground plane at the unit. The noninverting input of each channel I/V converter should also either connect directly to the analog ground plane or have an individual sense trace back to the $A_{GND}X$ pin connection. The feedback resistor trace to the I/V converter should also be kept short and have low resistance in order to prevent IR drops from contributing to gain error. This attention to wiring ensures the optimal performance of the DAC8812.

APPLICATION INFORMATION

The DAC8812, a 2-quadrant multiplying DAC, can be used to generate a unipolar output. The polarity of the full-scale output I_{OUT} is the inverse of the input reference voltage at V_{REF} .

Some applications require full 4-quadrant multiplying capabilities or bipolar output swing, as shown in Figure 35. An additional external op amp (A2) is added as a summing amp. In this circuit, the first and second amps (A1 and A2) provide a gain of 2X that widens the output span to 20 V. A 4-quadrant multiplying circuit is implemented by using a 10-V offset of the reference voltage to bias A2. According to the following circuit transfer equation (Equation 2), input data (D) from code 0 to full scale produces output voltages of $V_{OUT} = -10$ V to $V_{OUT} = 10$ V.

$$V_{OUT} = \left(\frac{D}{32768} - 1 \right) \times V_{REF}$$



Digital interface connections omitted for clarity.

A. Figure represents one channel only. X is channel A or B (i.e. $V_{REF\ X} = V_{REFA}$ or V_{REFB}).

Figure 35. Four-Quadrant Multiplying Application Circuit

Cross-Reference

The DAC8812 has an industry-standard pinout. Table 4 provides the cross-reference information.

Table 4. Cross-Reference

| PRODUCT | INL (LSB) | DNL (LSB) | SPECIFIED TEMPERATURE RANGE | PACKAGE DESCRIPTION | PACKAGE OPTION | CROSS-REFERENCE PART NUMBER |
|-------------|-----------|-----------|-----------------------------|---|----------------|-----------------------------|
| DAC8812ICPW | ±1 | ±1 | –40°C to 85°C | 16-Lead Thin Shrink Small-Outline Package | TSSOP-16 | N/A |
| DAC8812IBPW | ±2 | ±1 | –40°C to 85°C | 16-Lead Thin Shrink Small-Outline Package | TSSOP-16 | AD5545BRU |

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| DAC8812IBPW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| DAC8812IBPWG4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| DAC8812IBPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| DAC8812IBPWG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| DAC8812ICPW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| DAC8812ICPWG4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| DAC8812ICPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| DAC8812ICPWG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| DAC8812IBPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| DAC8812ICPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| DAC8812IBPWR | TSSOP | PW | 16 | 2000 | 367.0 | 367.0 | 35.0 |
| DAC8812ICPWR | TSSOP | PW | 16 | 2000 | 367.0 | 367.0 | 35.0 |

PW (R-PDSO-G16)

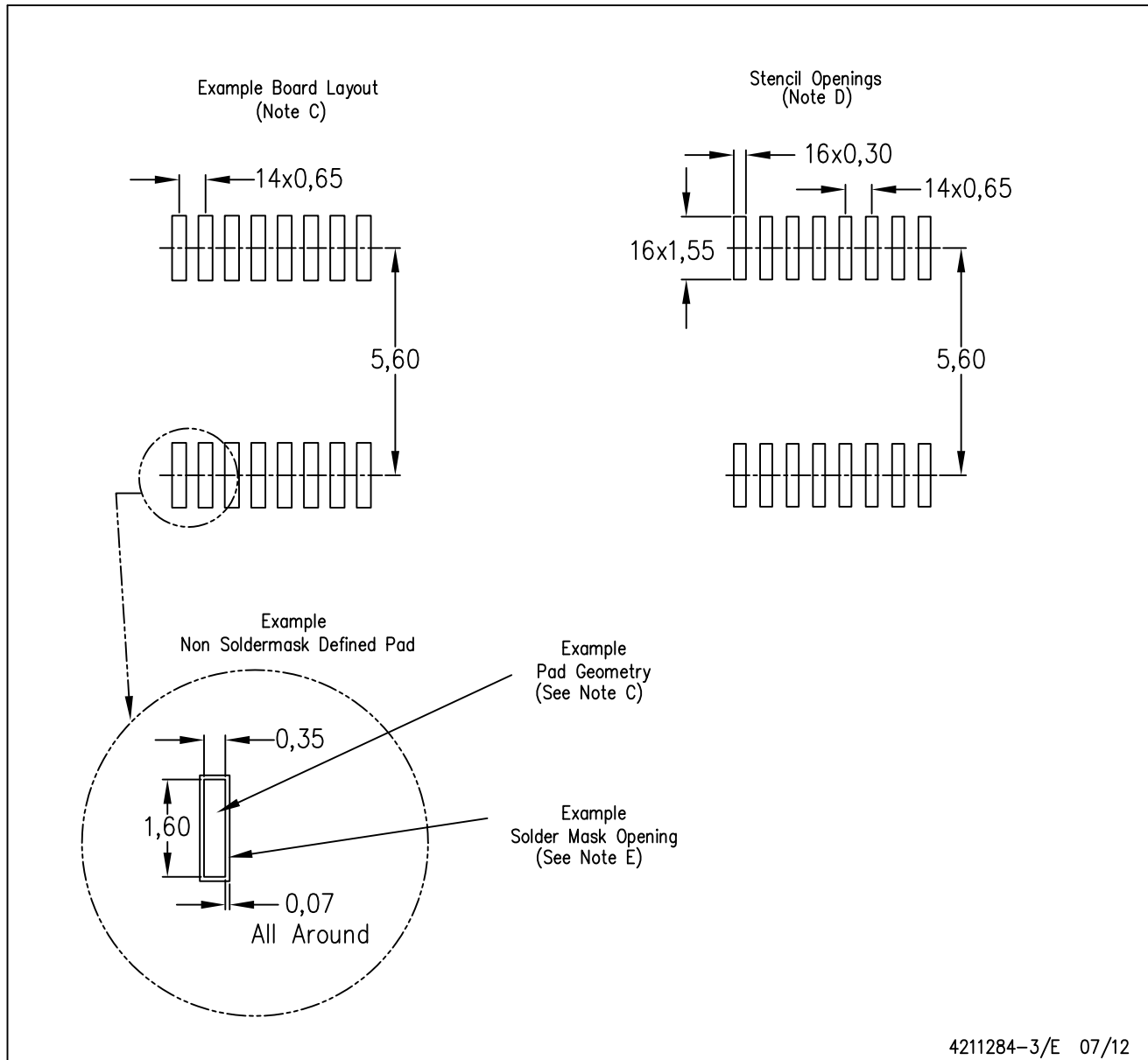
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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